ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNORS (Inventors):

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(nere	inafter 'Ass	signs and transfers to EPISTAR CORPO signee'), of (Assignee address) ve. II, Science-Based Industrial Park, Hsig					
, and	est in and to	sors assigns and legal representatives of the party and all improvements which are disclosured and all improvements are	ASSIGNEE the en osed in the invention	tire right, title, and nentitled:			
	"LIGHT I	EMITTING DIODE HAVING AN ADHESIVE THEREOF"	LAYER AND A MANI	UFACTURING			
Whi	ch is found	l in :					
(a) _	U	J.S. patent application executed on even date	e				
		J.S. patent application executed on					
(c)_	U.S. application serial no						
(d)_	pa	issued		-			

and, in and to, all Letters Patent to be obtained for said invention by the above application or ant continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

I WITNESS WHEREOF, We hagning).	ave hereunto set hand and seal this	_(Date
(Type name of inventor)	Signature of INVENTOR	
Min-Hsun Hsieh	Min-Assun Hsieh	
Tzu-Feng Tseng	Ten-Heng Tseng	
Wen-Huang Liu	Won Hung Sin	
Ting-Wei Yeh	Tray ich. Typh	
Jen-Shui Wang	Jen- Shui Wang	da sak sadak

COMBINED DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

I believe I am the sole (if only one name appears below), or joint (if more than one name appears), original and first inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

"LIGHT EMITTING DIODE HAVING AN ADHESIVE LAYER AND A MANUFACTURING METHOD THEREOF"

+ The specification for the	above entitled invention	is filed herewith.				
The specification for the						
with application serial number:	Filing					
I hereby state that I have specification, including the claims	reviewed and understand the , as amended by any amendm	contents of the above identified ent referred to above.				
I acknowledge the duty to disclose information which is material to the patentability of the invention disclosed in this application in accordance with Title 37, Code of Federal Regulations, Section 1.56 (a). I further acknowledge the duty in any continuation-in-part application to disclose to the Patent and Trademark Office all information known to be material to the patentability of the invention disclosed in this application, as defined in 1.56, which became available to me between the filing date of the prior application and the filing date of this application.						
	PRIORITY CLAIM	<u></u>				
There is no claim of priorit	y					
Claim of priority is based on the following: Division Application of No 10/604, 352						
Filing date: 2003/7/14						
POW	ER OF ATTORNE	EY				
application and to transact all relate	hereby appoint the following doubless in the Patent and T	g attorneies to prosecute this				
Winston Hsu	Registration# 41,526	<u> </u>				
Mord Michael Lewis	Registration# 50,478	MikeLewis@naipo.com.tw				
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DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued hereon.

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Date:	7.3. >03	Jen-Shai Wang
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